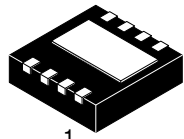


# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

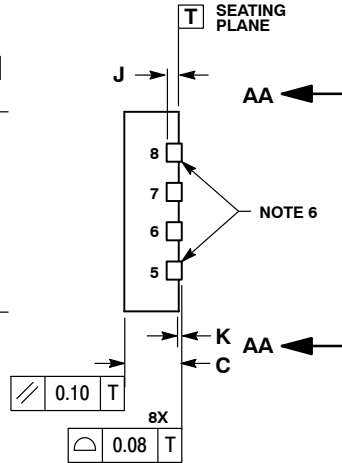
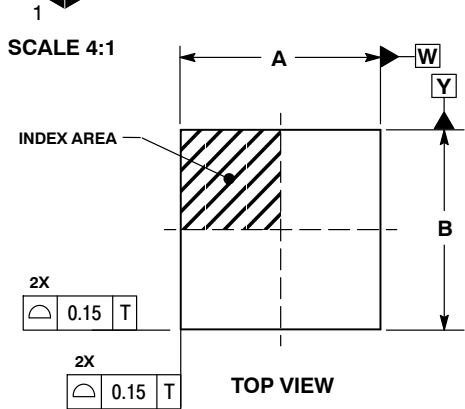
ON Semiconductor®



### DFN8 3x3, (MICRO8 LEADLESS)

CASE 846C-01  
ISSUE D

DATE 28 JUN 2010

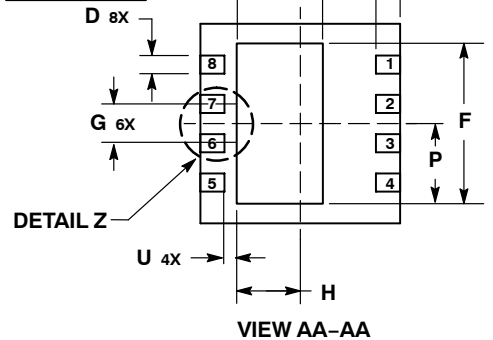


NOTES:

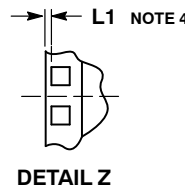
1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. THE TERMINAL #1 IDENTIFIER AND TERMINAL NUMBERING CONVENTION SHALL CONFORM TO JESD 95-1 SPP-012. DETAILS OF TERMINAL #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE TERMINAL #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE.
4. DIMENSION D APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.25 MM AND 0.30 MM FROM TERMINAL TIP. DIMENSION L1 IS THE TERMINAL PULL BACK FROM PACKAGE EDGE, UP TO 0.1 MM IS ACCEPTABLE. L1 IS OPTIONAL.
5. DEPOPULATION IS POSSIBLE IN A SYMMETRICAL FASHION.
6. OPTIONAL SIDE VIEW CAN SHOW LEADS 5 AND 8 REMOVED.

NOTE 4

0.10	T	W	Y
0.05	T	W	

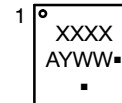


SIDE VIEW



DIM	MILLIMETERS	
	MIN	MAX
A	3.30	BSC
B	3.30	BSC
C	0.85	0.95
D	0.25	0.35
E	1.30	1.50
F	2.55	2.75
G	0.65	BSC
H	0.95	1.15
J	0.25	BSC
K	0.00	0.05
L	0.35	0.45
L1	0.00	0.10
P	1.28	1.38
U	0.17	TYP

### GENERIC MARKING DIAGRAM\*

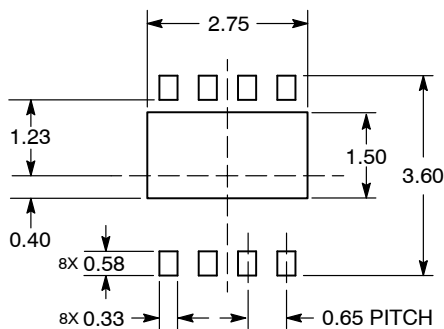


- XXXX = Specific Device Code
- A = Assembly Location
- Y = Year
- WW = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

### SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	DFN8 3X3, (MICRO8 LEADLESS)	PAGE 1 OF 1

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